STEVAL-CAM-M0I



Data brief

P-Board: Hardware MIPI CSI-2 kit for the evaluation and integration of promodules on embedded processing platforms





Order code	Description
STEVAL-CAM-M0I	P-Board hardware kit

Features

- Comprehensive hardware kit including:
 - Promodule board with input connector for camera modules and FFC output connector.
 - Ribbon cable to connect directly to embedded processing boards.
- Instant integration onto embedded processing platforms:
 - Native MIPI CSI-2 output and I²C communication interfaces.
 - FFC connector and associated cable provided for direct plug-and-play connection to the platform.
 - Various Linux drivers are available for free download on st.com to make software integration instant.
- A single and reusable solution for integrating all ST BrightSense solutions:
 - A single input connector that supports all ST promodules
 - Plug-and-play input connector to change sensor or lens instantly.
 - Promodule to be ordered separately.

Description

The P-Board is a versatile hardware kit for integrating seamlessly any ST BrightSense image sensor in the form of a promodule on embedded processing platforms. This comprehensive development solution includes a promodule board with MIPI CSI-2 output and a ribbon cable.

Featuring a MIPI CSI-2 output and I²C communication interface, the P-Board is natively compatible with embedded vision platforms. Hardware integration is immediate by plugging the standard FFC cable provided from the P-Board to the embedded processing board. Software integration is just as simple by using the various Linux drivers available for free download in the <u>Imaging Software</u> section of our website. This combination of hardware and software tools makes the P-Board the ideal development solution for Linux environments.

Relying on an FFC-to-board input connector, the P-Board allows users to integrate turnkey promodules instantly in a plug-and-play approach. The common connector and pinout shared by all ST promodules allow users to use the P-Board with any promodule. This convenient plug-and-play approach offers the opportunity to reuse this affordable kit at any time to integrate various sensor and lens combinations in the form of an evaluation camera module. With the P-Board, benefit from the flexibility to test or integrate various sensors by just plugging and unplugging camera modules.



Figure 1. Typical setup for using the P-Board on embedded processing platforms



Figure 2. Content of the P-Board deliverable

Item 1: P-Board	Item 2: FFC cable
Camera module input connector (for use with promodules) FFC output connector GPIO connector	

Table 1. Main technical specifications

Category	Item	Parameter	Specification
Electronics	Board input	Connector type	Board to board/FFC
		Pinout	30 pins
		Connector reference	BM28B0.6-30DP/2-0.35V by Hirose
		Image input format	MIPI CSI-2
		Control interface	l²C
		Compatible evaluation tools	CAM-55G0, CAM-55G1, CAM-56G3, CAM-66GY
	Board output	Connector type	FFC
		Pinout	22 pins
		Connector reference	FH12-24S-0.5SH(55) by Hirose
		Image output format	MIPI CSI-2 (1 or 2 lanes)
		Control interface	l²C
	Cable	Cable pinout	22 pins ⁽¹⁾
		Cable reference	687722050002 by Würth
Mechanics	Board	Dimension - L x H x W	30 x 35 x 11 mm
wechanics	Cable	Length	10 cm

1. Other pinouts (ex: 15 pins) can be supported by plugging different off-the-shelf cables available from various suppliers.

Revision history

Table 2. Document revision history

Date	Version	Changes
11-Jun-2024	1	Initial release

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